Ball-Wedge Bonder

5810

Bond System

Wire types	Gold wire 12,5-50µm on 2” spool
Bondhead	Ball-Wedge for gold wire Standard capillaries 16mm length (optionally 19 mm)
Ultrasonic System	F&S Generator 67kHz (optional 120, 130, 140kHz)

Bonder Base

Axes

- Working area X/Y-axis 200 x 150 mm;
- Programmable step resolution 1µm
- Programmable Z axis with 100 mm stroke;

Hardware

- Dual-Core PC with Windows OS, Ethernet,
- USB 2.0/3.0, Colour Display 22”
- GigE-CCD-Colour Camera, 5 Mpixel
- Fully networkable in TCP/IP servers

Software

- From single bonds up to complex programmes,
- Loop shapes can be saved in libraries
- Optional pattern recognition

Control

- high-performance embedded ARM-System with Real-time operating system for precision
- 1 wire / second

Placement accuracy:	+/- 5µm @ 3 sigma, incl. Tool / no wire on F & S Bondtec standard substrate
Repeatability:	+/- 3 µm @ 3 sigma, incl. Tool / without wire on F & S Bondtec standard substrate
Loop height accuracy:	+/- 5µm @ 3 sigma, for thin wire 5830 with 25µm aluminum wire on F & S Bondtec standard substrate

The 58xx series:

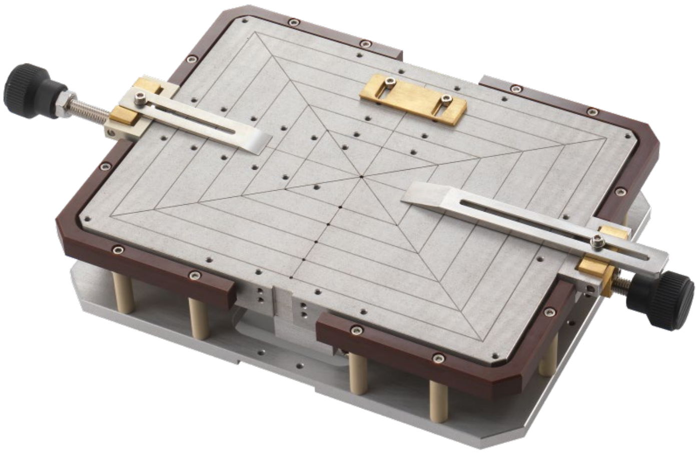
The Gold wire Ball-Wedge version of the automatic wire bonders in our Series 58xx featuring exchange able bond heads.

A fully automatic mode makes it ideally suited for medium-scale production. Parts to be bonded are fed manually by the operator, but the bonds are produced completely without operator influence.

Thanks to the built-in pattern recognition. Single bonds can be made within seconds, making the machine perfect for R&D, Pilot manufacturing and middle volume production.

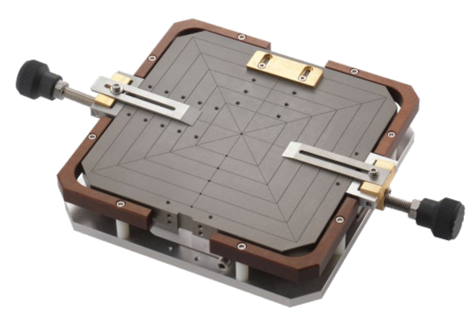
Dimensions	W x D x H 92x71x65 cm, weight approx. 80 kg
Connections	100-240 VAC, 1 Phase, 50/60 Hz, max 230 VA Ø 6 mm standard vacuum tubing
Heater controller	integrated in the machine 0-250°C

Workholder

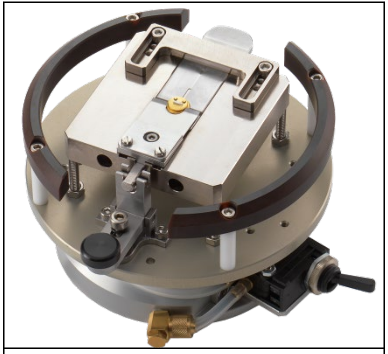


Standard-Workholder
for parts up to 8x6“
with Vacuum und mechanical clamping

Optional:



6x6“workholder with Vacuum and mechanical clamping



TO Workholder with mechanical clamping

4x4“ workholder with . rubberized surface and mechanical clamping

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